3D Packaging and Integration Global Technical Committee

Japan TC Chapter Meeting

Japan Standards Spring 2022 Meetings

Monday, May 16, 2022,

Web conference

To be conducted by Official Virtual TC Chapter Meeting

14:00-17:00 Japan Standard Time

AGENDA

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Cycle 2-2022 submitted by the Japan TC Chapter

5.1.1 Document 6867 - Reapproval of SEMI G86-0217, Test Method for Measurement of Chip (Die) Strength by Mean of 3-Point Bending

6 Task Force & Study Group Reports

6.1 GCS

6.2 3D Packaging & Integration 5 Year Review Task Force

6.3 3DS IC Bonded Layer Inspection Metrology Task Force

6.4 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

6.5 Panel Level Packaging (PLP) Glass Carrier Task Force

6.6 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check

8 New Business

8.1 Report of Ratification Ballot Result

8.1.1 R6703A - Revision to SEMI G63-95 (Reapproved 0811) Test Method for Measurement of Die Shear Strength

8.1.2 R6706 - New Standard Specification For Coefficient Temperature Expansion (CTE) Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.3 R6707 - New Standard: Specification For Flowability Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.4 R6708 - New Standard: Specification For Gel Time Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.5 R6709 - New Standard: Specification For Modulus Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.6 R6710 - New Standard: Specification For Shear Strength Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.7 R6711- New Standard: Specification For Viscosity Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.8 R6712 - New Standard: Specification For Wettability Of Encapsulation For Wafer Level Packaging And Panel Level Packaging

8.1.9 R6858 - Revision to SEMI G13-88 (Reapproved 0811) with Title Change from “Standard Test Method for Expansion Characteristics of Molding Compounds” to: “Test Method For Thermal Expansion Characteristics Of Molding Compounds”

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment